



Docket No.: M4065.0082/P082-A
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Paul A. Farrar

Application No.: 09/638,026

Filed: August 14, 2000

For: METHOD OF FORMING A MICRO
SOLDER BALL FOR USE IN C4
BONDING PROCESS

Group Art Unit: 2811

Examiner: N. Parekh

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J. McMillan
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AMENDMENT AFTER FINAL REJECTION

Box AF
Commissioner for Patents
Washington, DC 20231

Dear Sir:

In response to the Office Action dated March 26, 2002 (Paper No. 4), finally rejecting claims 40-51 and 68-73, please amend the above-identified U.S. Patent application as follows:

In the Claims

Please cancel claims 41-42 and 73.

Please amend the following claims as indicated.

40. (Amended) A semiconductor device comprising:

a semiconductor structure having at least one metal contact formed on a surface thereof;